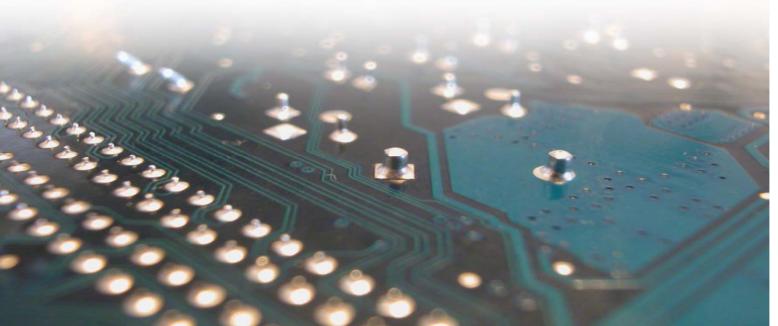
#### Adapting Signal Integrity Tools and Techniques for 6 Gbps and Beyond

Donald Telian - SI Consultant



Session 8.3

### Agenda

- Why Serial Links?
- SI Moving Inside ICs
- Gbit Simulation Today
- Looking Forward

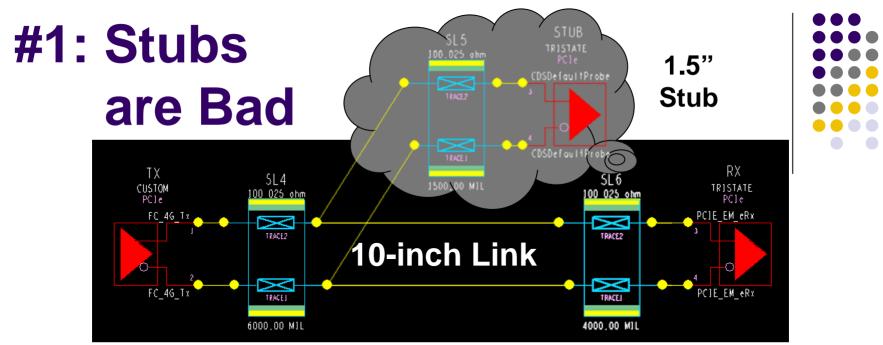


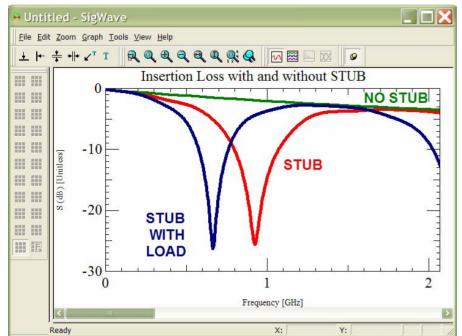
### Agenda

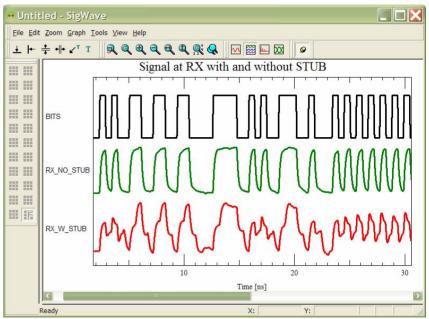


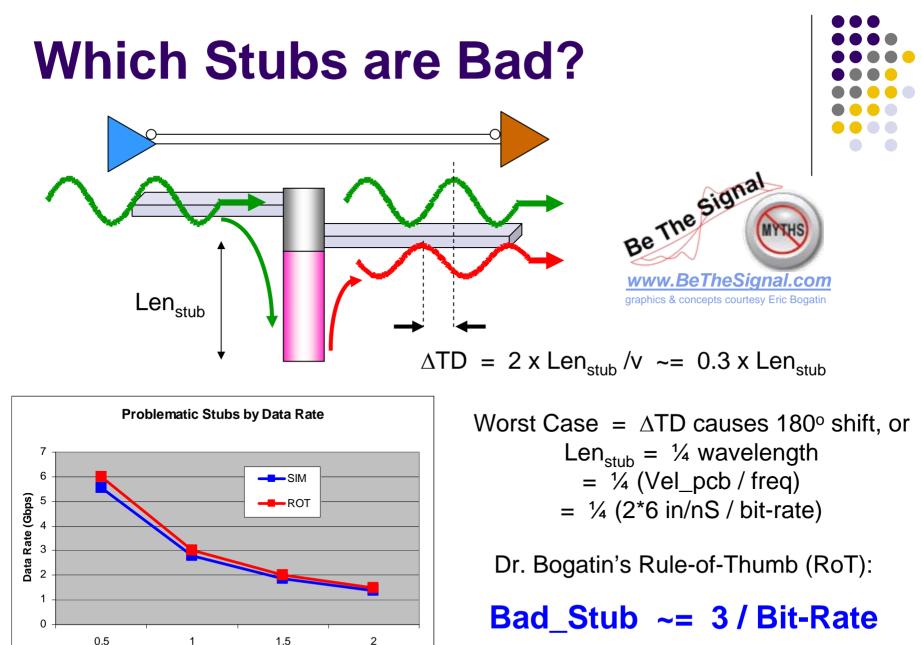
- Stubs are Bad
- Signals are Ugly
- Gates are Free
- SI Moving Inside ICs
- Gbit Simulation Today
- Looking Forward







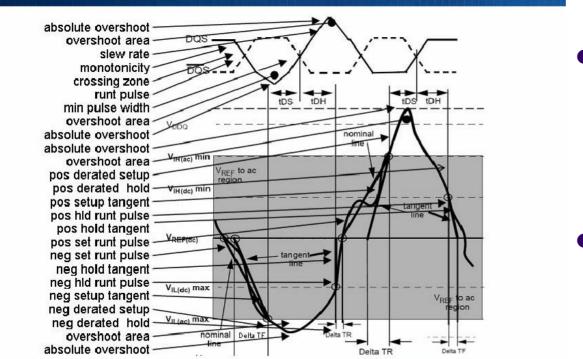




Or, OK\_Stub ~= 3 / (10\*Bit-Rate) xxx\_Stub in inches, Bit-Rate in Gbps

Donald Telian SI Consultant

Stub Length (inches)

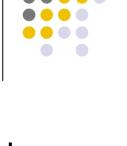


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석카일

#### #2: Signals are Ugly

#### **Required DDR2 Measurements**

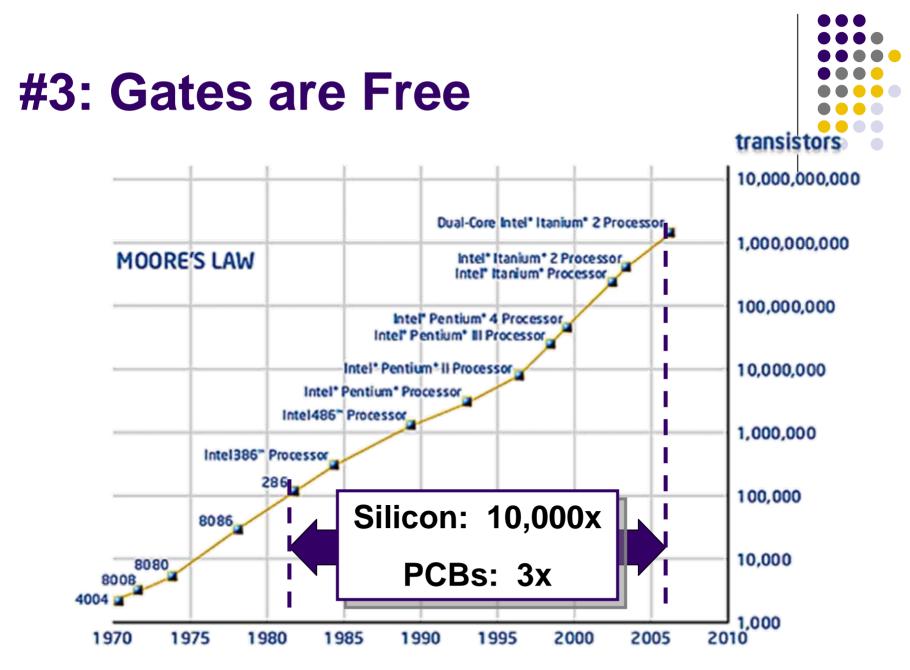


- High-speed signals need post-processing
- Shall we do that during design?
   ...or in silicon?

#### Receiver's behavior and specifications are sensitive to these effects

Micron

Source: "Single Simulation Analysis of a DDR2 Interface in IBIS 4.1" from DesignCon 2007, courtesy Randy Wolff, Micron Slide 6



#### **The Turning Point**

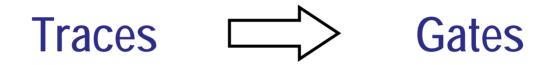




"We're now at the point where it's getting cheaper to put more gates behind a fast serial line than to lay down copper traces."

Jim Pappas, Intel

 – commenting on why PCI Express used serial technology and PCI used parallel – EETimes February 18, 2002 page 92



#### Why Serial Links?



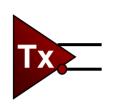
- Stubs are Bad
  - Frequency issues arise with stubbed interconnects
    - As early as 400 MHz, see <u>DesignCon 2006 Best Paper</u>
  - The point-to-point nature of serial links removes stubs
- Signals are Ugly
  - Receiving high-speed signals is challenging
  - Serial links use built-in filtering to recover signals
- Gates are Free
  - Surplus silicon has added features to IO transceivers
  - Signal Integrity is moving inside the chip

### Agenda

- Why Serial Links?
- SI Moving Inside ICs
  - Transmitters (Tx)
  - Receivers (Rx)
  - Gbit Simulation Today
  - Looking Forward

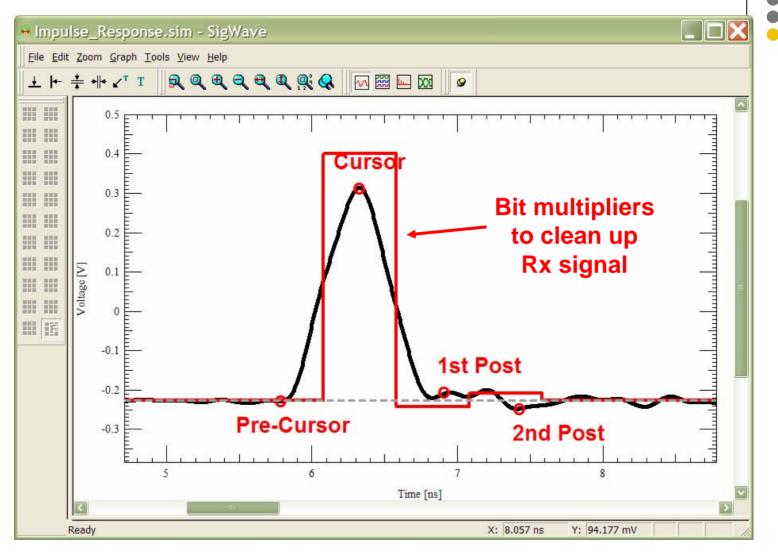


#### **Tx Techniques**



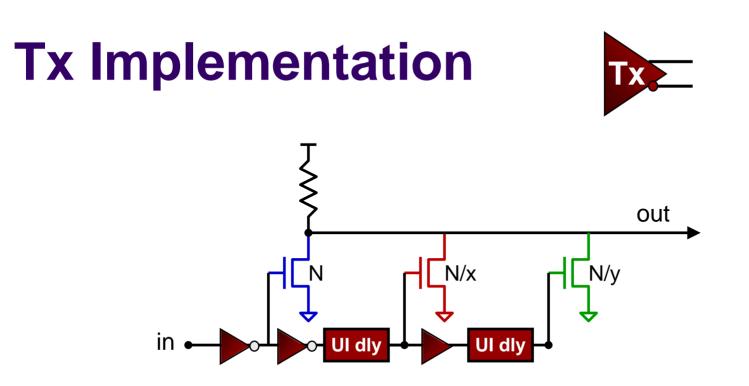
- Adapting signal at Tx is simpler than Rx
  - Data pattern is known
- Around 2.5 Gbps "pre-emphasis" was used
  - Sometimes called "de-emphasis" or "2-taps"
- At higher rates, more "taps" are used
  - Some taps before bit, or "pre-cursor"
  - Taps typically spaced by bit times
- Most efficient when Rx signal understood
  - Through simulation, spec boundaries, etc.

#### **Taps & Impulse Response**





Slide 12



- Bit-stream fed directly to SerDes
- For more detail, see Cadence webinar
  - How to build fast and accurate multi-gigabit transceiver models

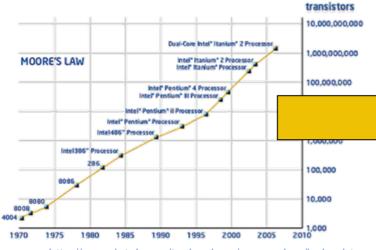
#### **Rx Techniques**



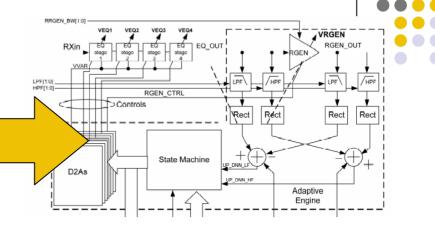


- Rx Equalization (EQ) is more challenging
  - Data pattern is NOT known
  - Signal at Rx has often disappeared
    - typically 20 dB down (10% of signal) at 6+ Gbps
- Primary area of SerDes advances
  - Higher speeds = more creative solutions
  - Techniques increasingly complex and/or non-linear
    - DFE = Decision Feedback Equalization
    - Some are continuously adaptive
    - Implementations inconsistent

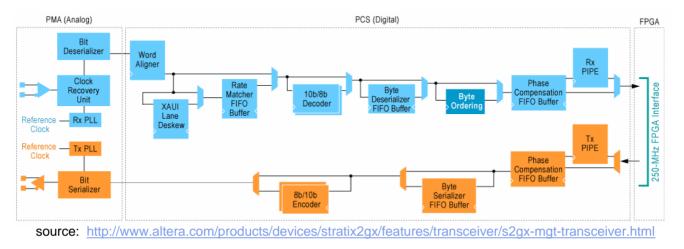
#### **Moore's Law Meets IO Interfacing**



source: http://www.intel.com/technology/mooreslaw/index.htm

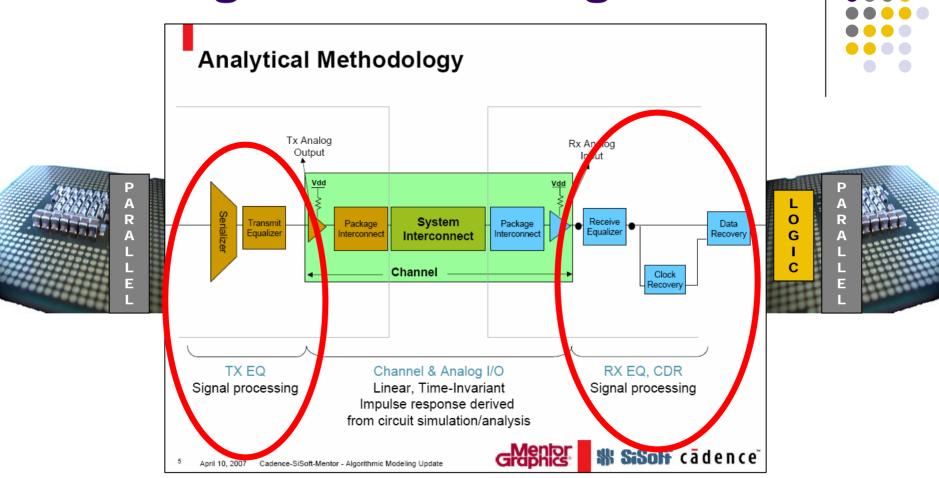


source: DesignCon 2007 Paper "Digitally Assisted Adaptive Equalizer in 90 nm With Wide Range Support From 2.5 Gbps to 6.5 Gbps" see <u>http://www.altera.com/literature/cp/cp-01026.pdf</u>



#### An increasing amount of transistors are consumed by signal transmission

#### **IO = Signal Processing?!**



Source: http://www.vhdl.org/pub/ibis/macromodel\_wip/archive/20070410/toddwesterhoff/Algorithmic%20Modeling%20BIRD%20-%20Update/IBIS-ATM\_Apr10-v3.pdf

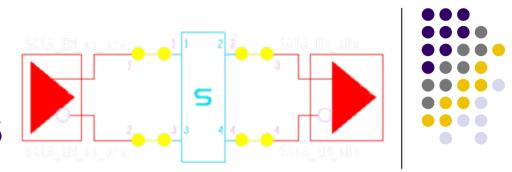
There's a lot of gates between serial and parallel
Communications theory has met the digital IO

### Agenda

- Why Serial Links?
- SI Moving Inside ICs
- Gbit Simulation Today
  - Outside the IC
  - Inside the IC
  - Signal Processing
  - Looking Forward

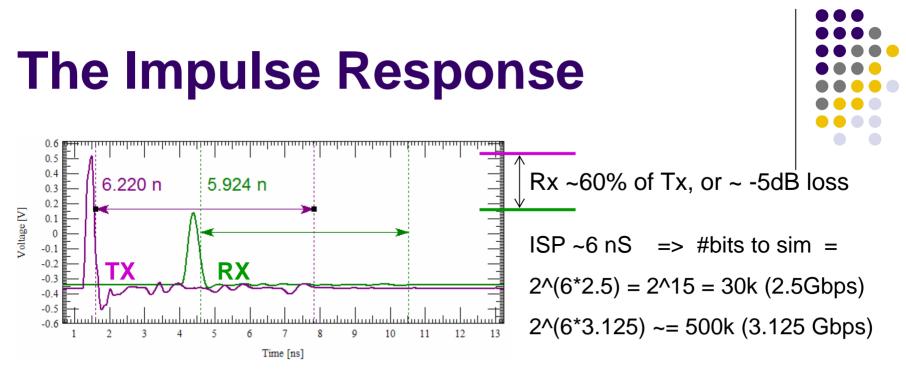


### Outside the IC = S-Parameters



#### • S-params common for passive interconnect

- Lab characterization covered for absence of tools
- Generated by both measurement and analysis tools
- Viewed as better than cascaded discrete models
- Can read loss directly from S-param plots
- Format for industry-standard "channels"
- Now handled by most PCB analysis tools
  - Some more mature than others
- Proper fixturing/measurement is challenging
- For more details see Cadence webinar
  - Understanding and Using S-Parameters for PCB Signal Integrity

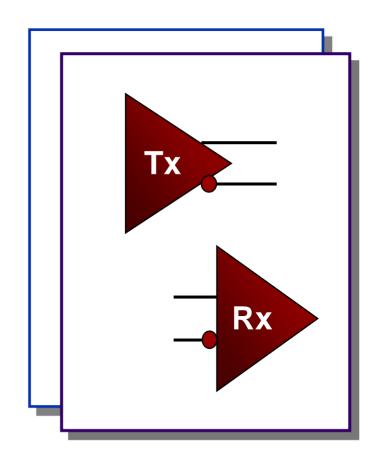


- System interconnect's "fingerprint"
- Reveals Tx to Rx "loss" (similar to eye or S\_21)
- Reveals "Interconnect Storage Potential (ISP)"
  - From which we can determine # bits to simulate
  - ISP detailed in Intel/Cadence DesignCon 2005 paper <u>"New Techniques for Designing and Analyzing Serial Links"</u>
- Used in <u>"high-capacity" simulators</u>



### **Understanding Analog Tx/Rx**

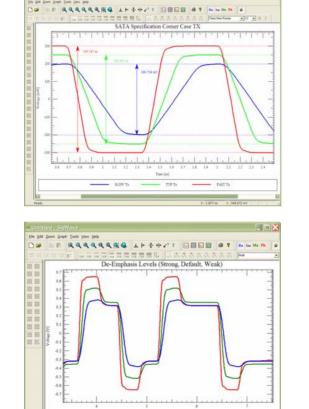
- The simple IO had a set of characteristics
  VI, T rf (VT), C comp
- And the differential Tx and Rx do too
  - V\_swing, T\_rf, V\_cm, R\_term, Pre-emp%, Cpad
- Same Tx/Rx handles multiple standards
  - Excessively programmable

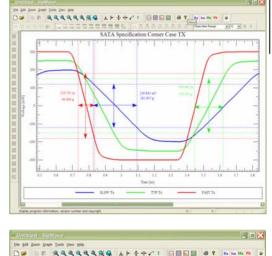


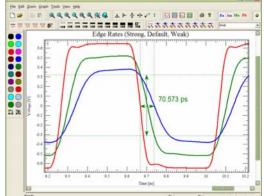
#### **Using "Spec" Models**

SATA Spec Voltage Swing & Edge Rates

~PCI Express Voltage Swing & Edge Rates







- <u>Craft</u> from base set of parameters in Specs
- Set of model templates at this link

### Beyond Analog Tx/Rx ~ Modeling Signal Processing

- Tools and models exist within IC companies
  - Used for IC architecture and design
- Excessively proprietary
- In some cases they're offered to customers
  - Support issues
  - Maintenance issues
- THE BIG ISSUE
  - Require same IC (vendor) on both ends of the link



#### **Interoperability Challenge**



- Must simulate models from different vendors
- It happened once before with "IBIS"
  - Early '90s many IBIS-like SI simulators emerged
  - Plug n Play SI required consistent model format
  - IBIS was born
- Once again the leaders are deriving a format
  - Executable "Algorithmic Models" contained in DLLs
  - All work in public domain done by IBIS-ATM
     IBIS Advanced Technology Modeling Task Group

### Agenda

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#### **Towards Interoperability**

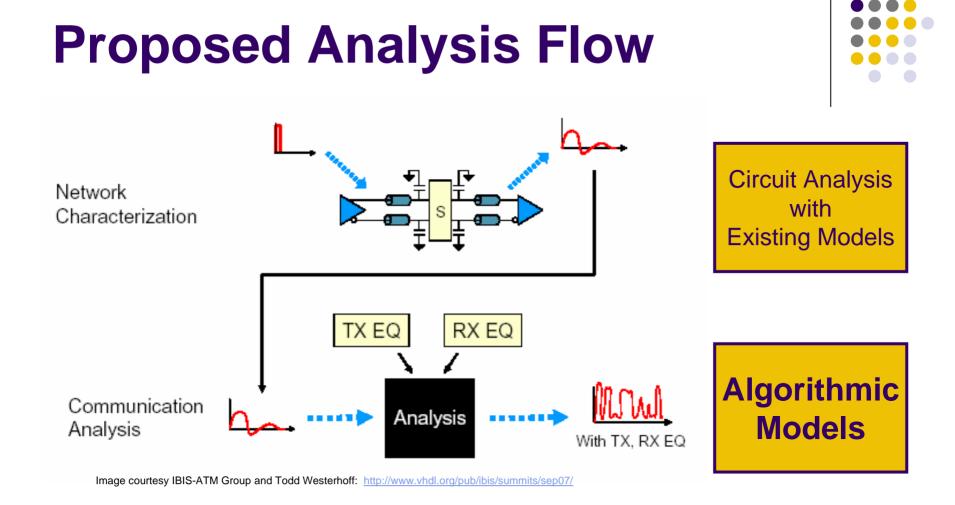


#### **IBIS-ATM SerDes Task Group**

- Goal: SerDes Rx/TX model interoperability
  - Multiple EDA platforms
  - Multiple SerDes vendor models
  - Protect SerDes vendor IP
- IBIS-ATM committee participation
  - EDA: Agilent, Cadence, Mentor, SiSoft
  - Semiconductor: IBM, Intel, Micron, ST-Micro, TI, Xilinx
  - System: Cisco
- Two part modeling standard
  - Characterization model: existing IBIS syntax models TX / RX analog characteristics
  - Algorithmic model: equalization, clock recovery, device optimization algorithms

Slide courtesy IBIS-ATM Group and Todd Westerhoff: <u>http://www.vhdl.org/pub/ibis/summits/sep07/</u>

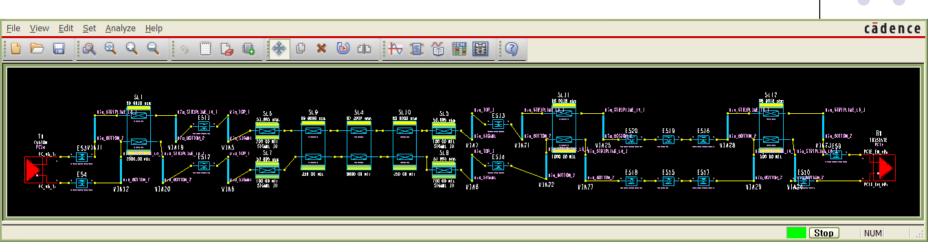
• IBIS-ATM: <a href="http://www.vhdl.org/pub/ibis/macromodel\_wip/">http://www.vhdl.org/pub/ibis/macromodel\_wip/</a>



Algorithmic models typically implemented in .dll files

#### Algorithmic Models Within Cadence Flow

cādence



- Algorithmic models fit within existing MGH flow
  - Invoked as part of Channel Analysis, some scripts etc.
- Cadence demo'd in Jan07, released in 16.0
- Tx/Rx macromodels contain "ami" portion
  - Includes path to dll file and settable parameters
- Cadence working towards industry standardization
  - Within IBIS domain (proprietary solution for now)

#### **Industry Standardization**

#### **IBIS-ATM Status**

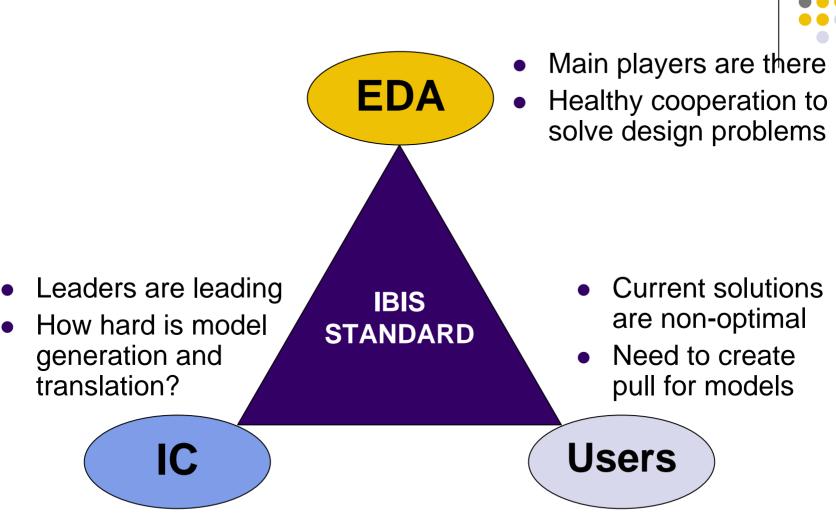
 Original proposal submitted by Cadence & IBM Current version authored by Cadence, Mentor, SiSoft First draft of BIRD approved by IBIS-ATM task group for prototype model & EDA platform development Prove interoperability & refine proposal before bringing back to IBIS Open Forum Subcommittee work, presentations & BIRD available on-line: http://www.vhdl.org/pub/ibis/macromodel\_wip/ Public TX/RX models, modeling "toolkits" will be available

Status courtesy IBIS-ATM Group and Todd Westerhoff: http://www.vhdl.org/pub/ibis/summits/sep07/

- Achieved model/EDA interoperability in Aug 2007
- Updated proposal (BIRD) for ATM approval ~Sep/Oct 2007
- ...and then on to IBIS committee approval and release



#### **SerDes SI into Mainstream**



Pieces are coming into place to enable push past 6 Gbps

#### **Existing Solutions**



- IBM offers Algorithmic Models for their 6 Gbps and 11 Gbps SerDes NOW
  - Operates within Allegro PCB SI 16.0
  - Available only to IBM customers
    - Contact your local IBM representative to obtain models
- IBIS-ATM group released AMI model Eval Toolkits
  - Visit the Work Archive at: <u>http://www.vhdl.org/pub/ibis/macromodel\_wip/</u>

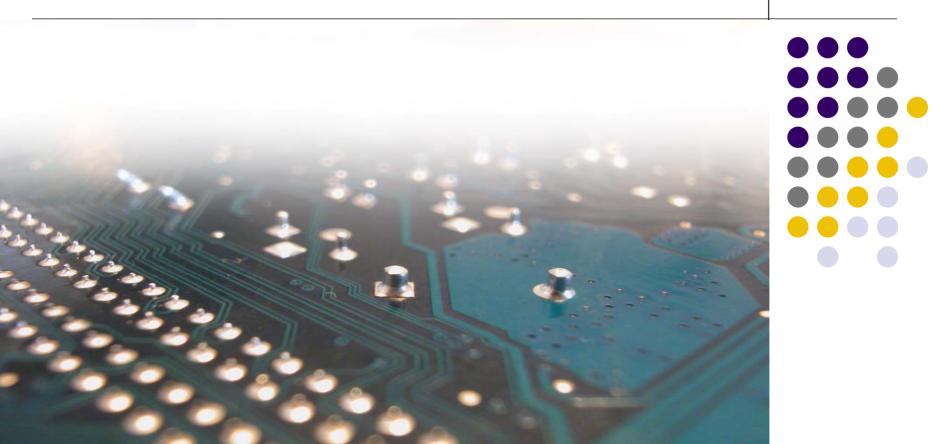
#### In Summary

- Serial links dominate for higher speeds
- Signal integrity moving inside chips
- Models, methods, metrics changing
- SerDes now do signal processing
- Interoperable models an issue
- Cadence/others driving a solution
- Algorithmic models coming into place





## THANK YOU





cadence designer network



# CONNECT: IDEAS

#### **CDNLive! 2007 Silicon Valley**